

Miniaturization and Advances of Bulk Head Mounted EMI Filters:

Material, Process, Design

R. Demcko, R. Edily

AVX Corporation

One AVX Boulevard

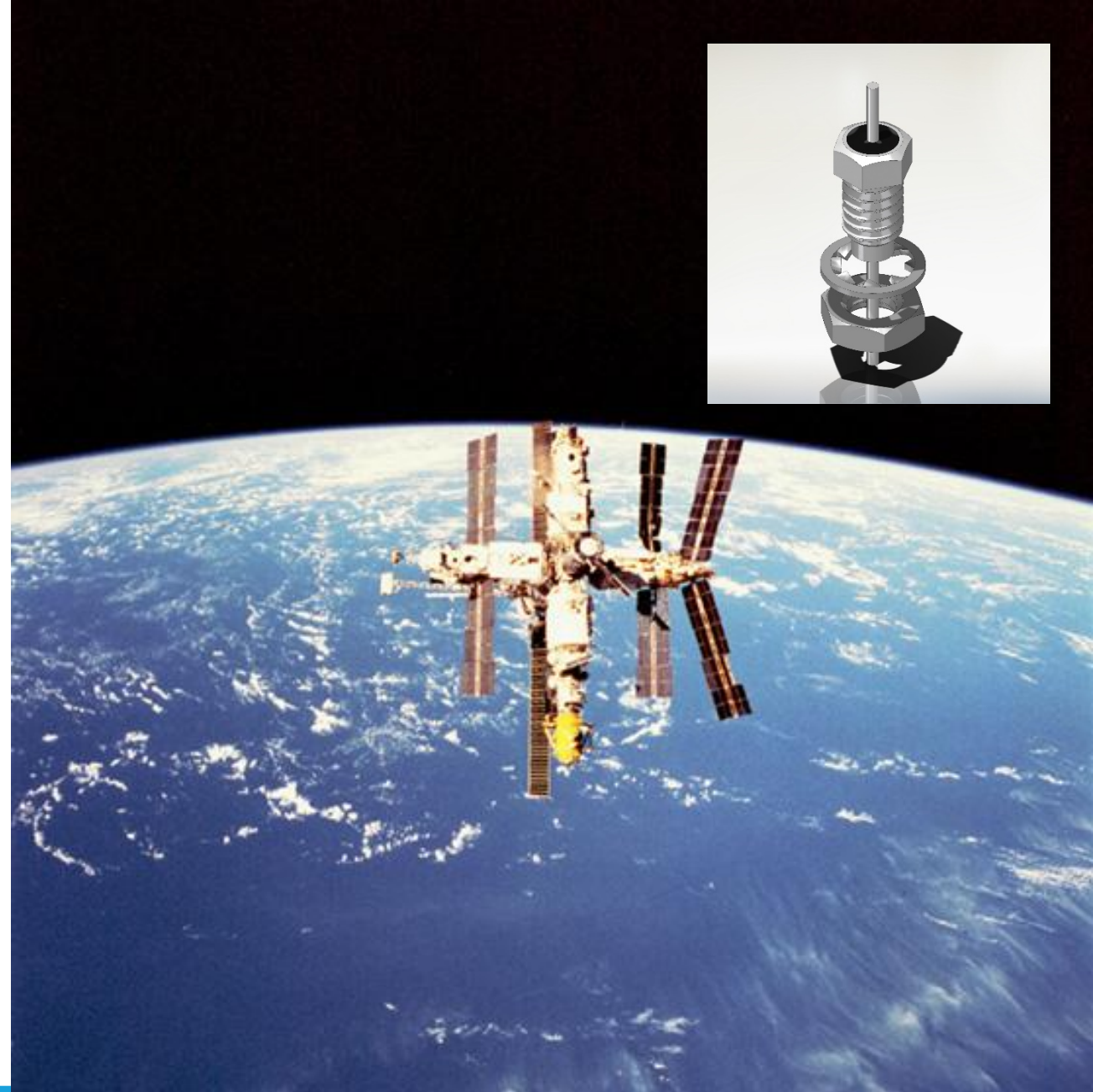
Fountain Inn, S.C. 29644 USA

Ron.Demcko@avx.com



Outline

- Filter Designs
- Performance
- Miniature Filters & Trends
- Summary

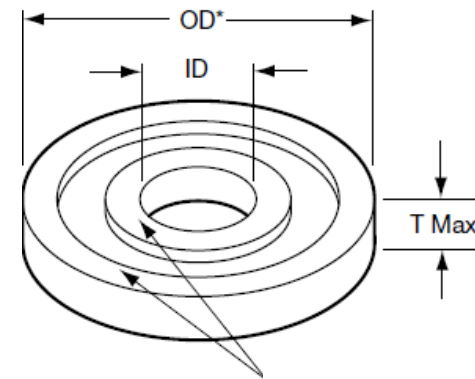


Bulk Head Filters:

Building block = Discoidal insert



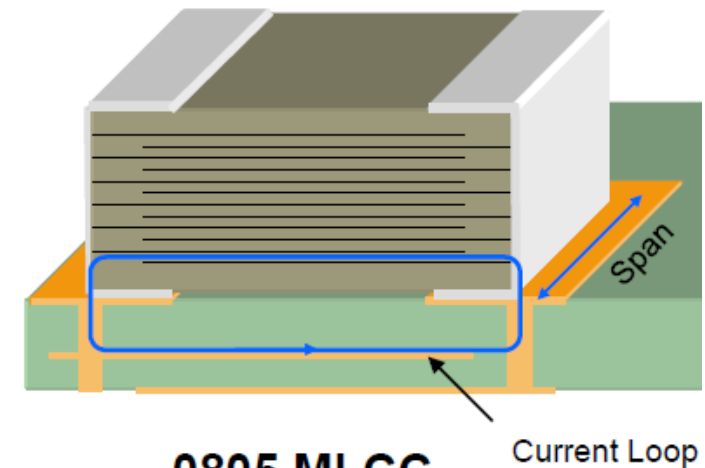
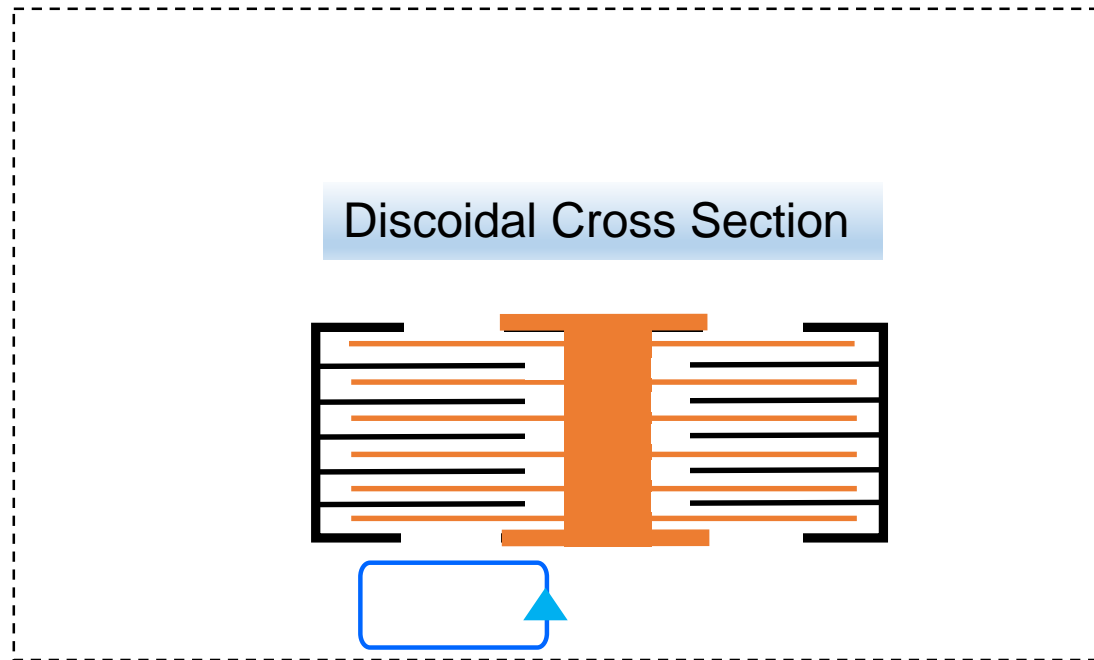
Discoidal Cross Section



Terminations

Bulk Head Filters:

Discoidal inserts are inherently low inductance vs MLCCs



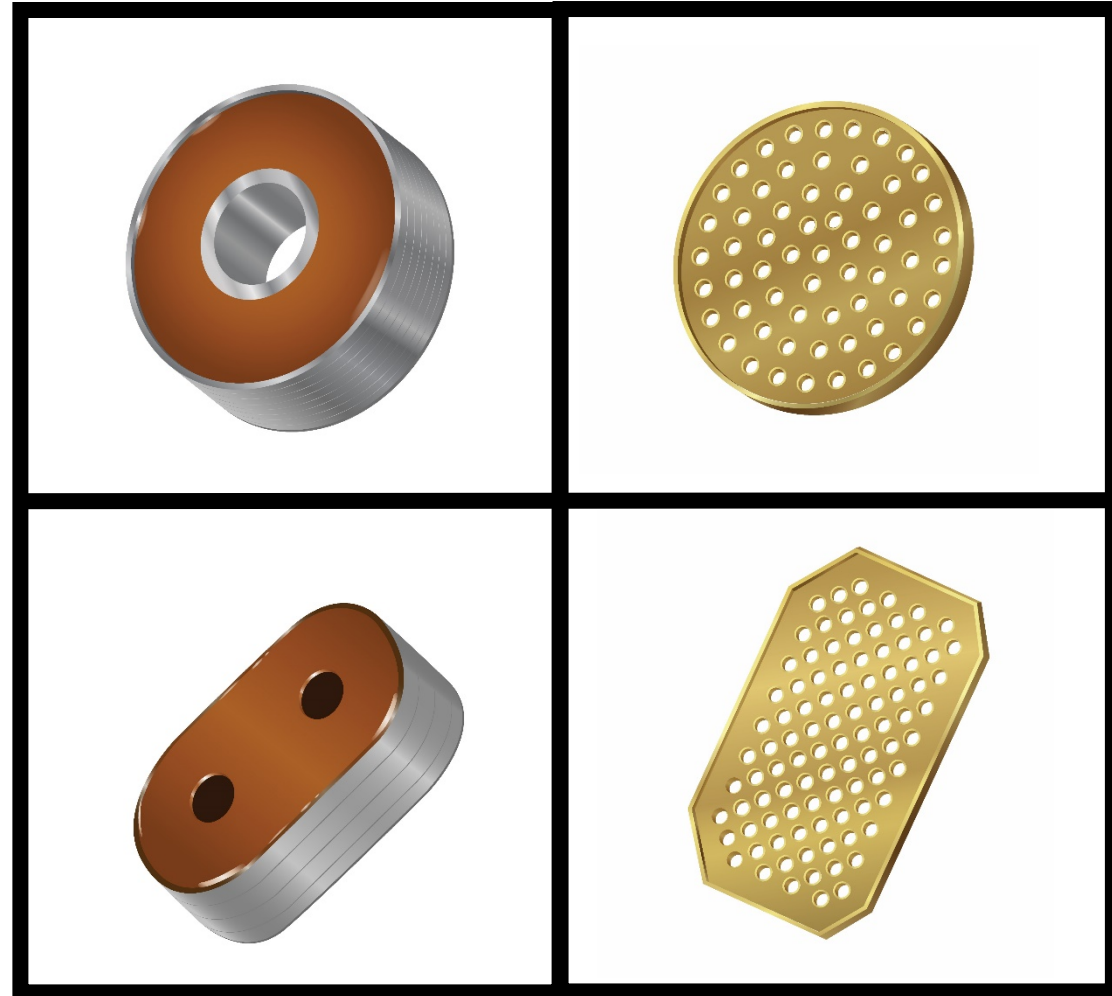
0805 MLCC
ESL ~525 pH

MLCC advances impact on inserts:

Smaller size

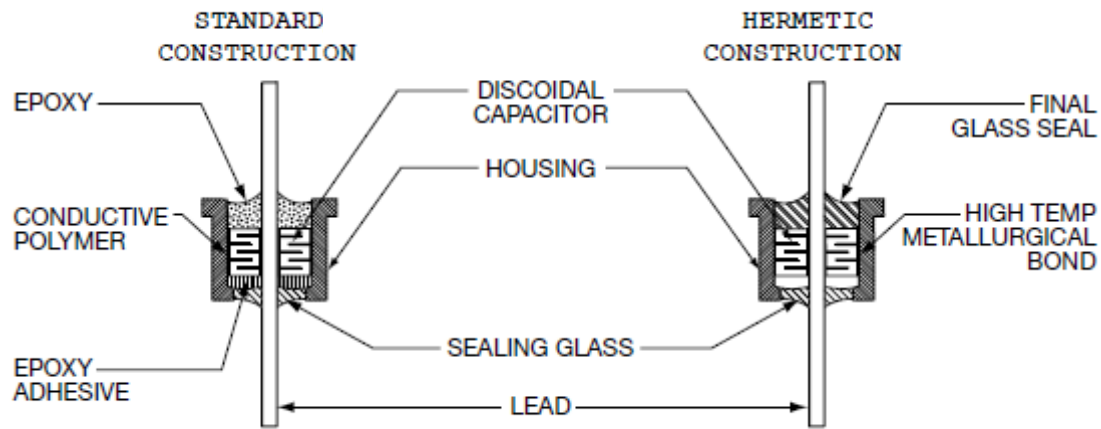
More complex patterns

Increased CV



Bulk Head Filters:

Discoidal used to create 3 Bulk Head styles



Bolt In



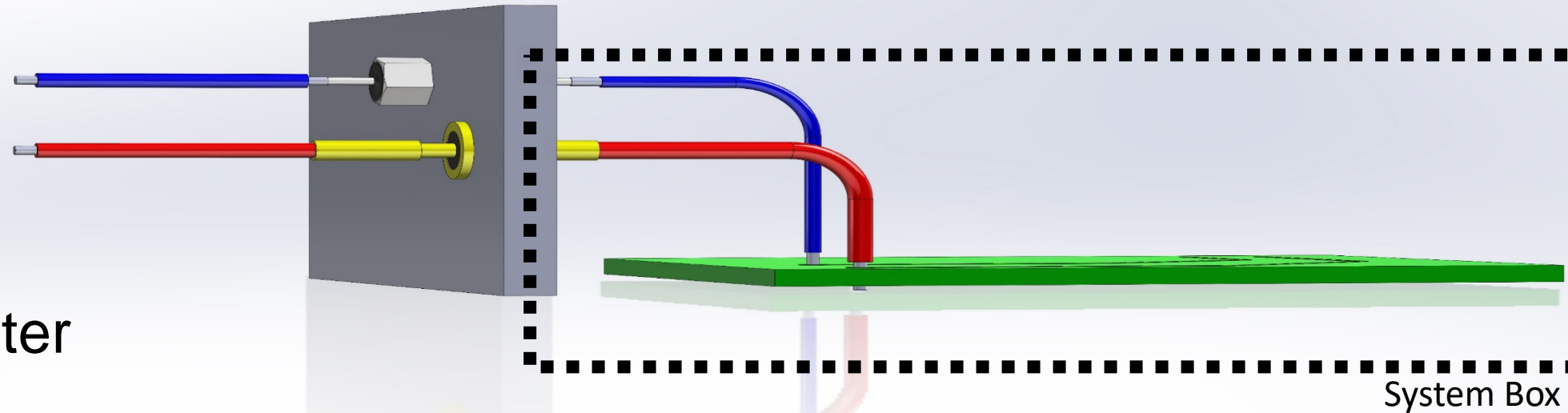
Solder in



Plate



Typical use:



System Level Filter

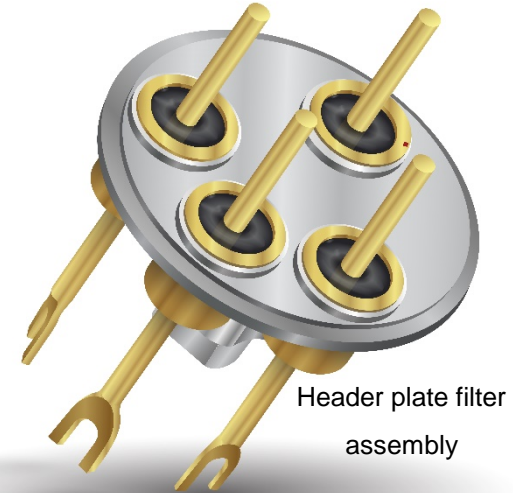
Ideal configuration / efficiency

Impacted positively by MLCC progress

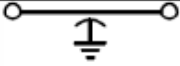


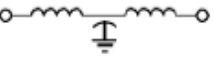
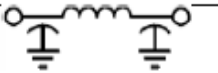



Bulk Head Filters:

General Characteristics

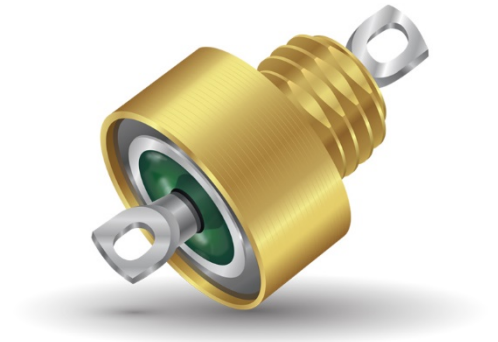
- Hermetic & Non Hermetic
- DC to 26Ghz range
- L,C structure based
- Installation temperatures to +400c
- Operating ranges -55c to +200c
- Commercial, Military & Space



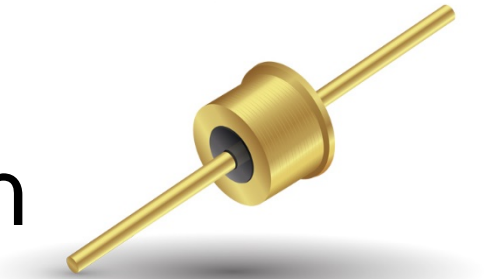
Bulk Head Filter configurations:

Filter Type	Schematic Symbol
Capacitor	
Inductor	
Wire	 ●
T Configured	
Pi Configured	
L-C	
C-L	
Transient Clamp	 ●

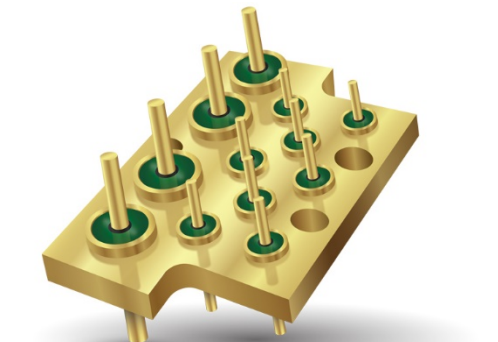
Bolt In



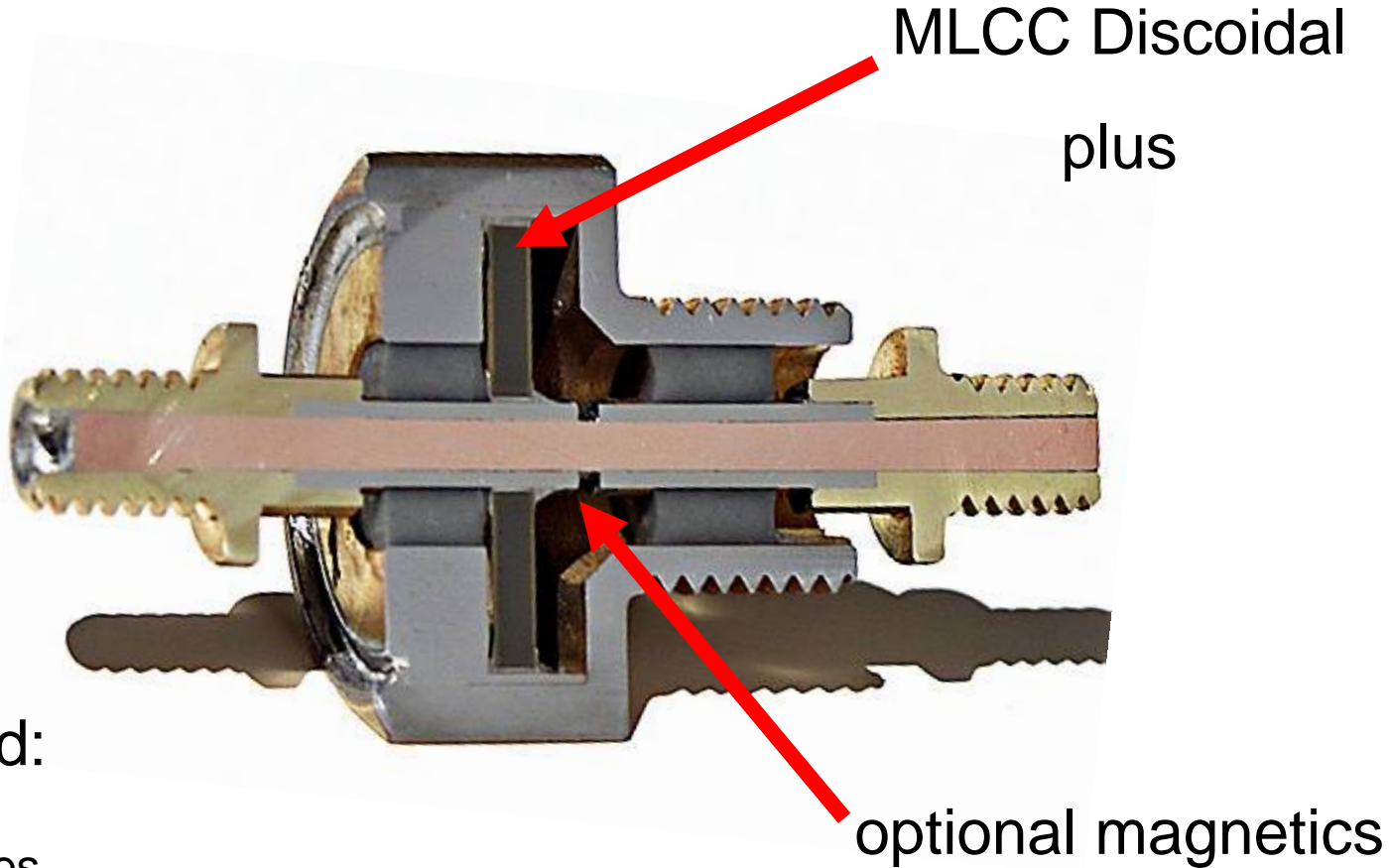
Solder in



Plate



Design:



MLCC advances yield:

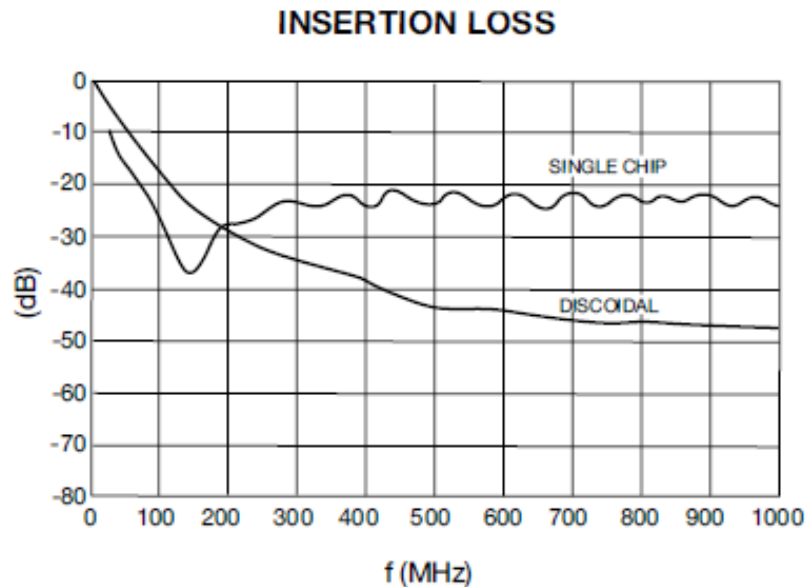
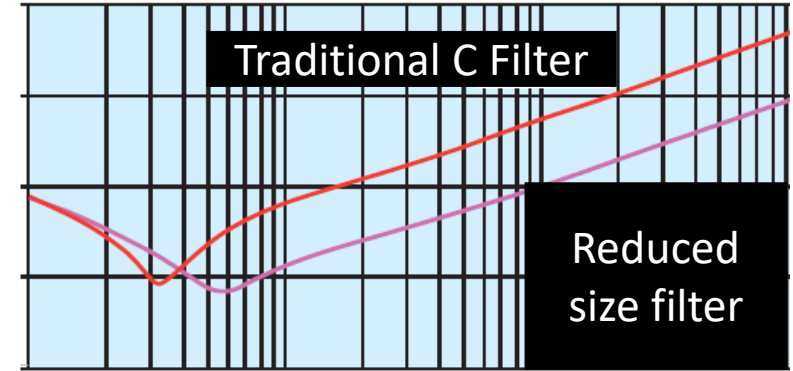
- smaller inserts
- Higher capacitance values

Design:

MLCC advances enable:

smaller discoidal → smaller bulk head filter → higher frequency response

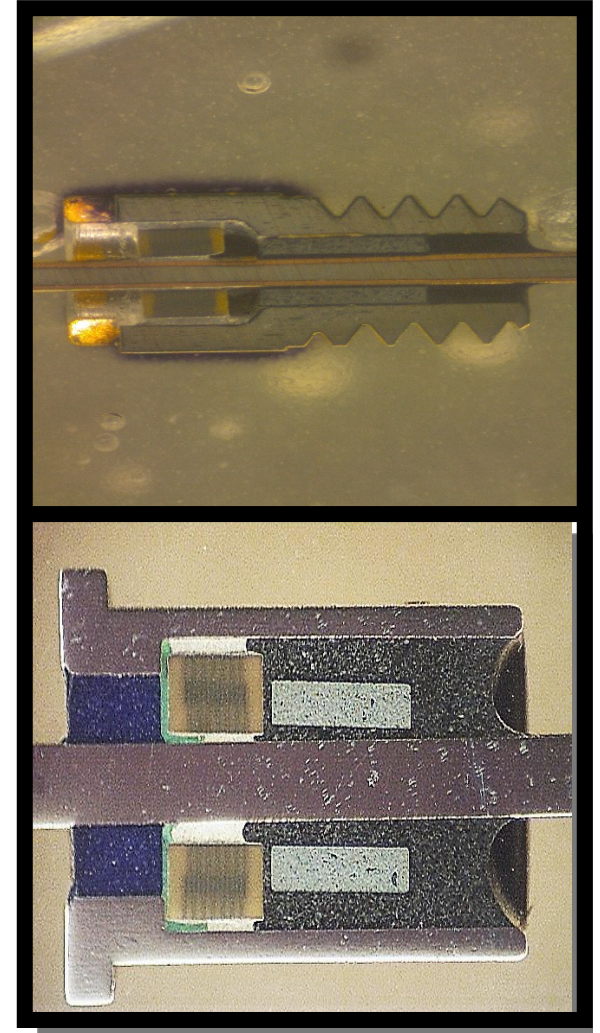
Low loss discoidal inserts → improved response over MLCC based filters



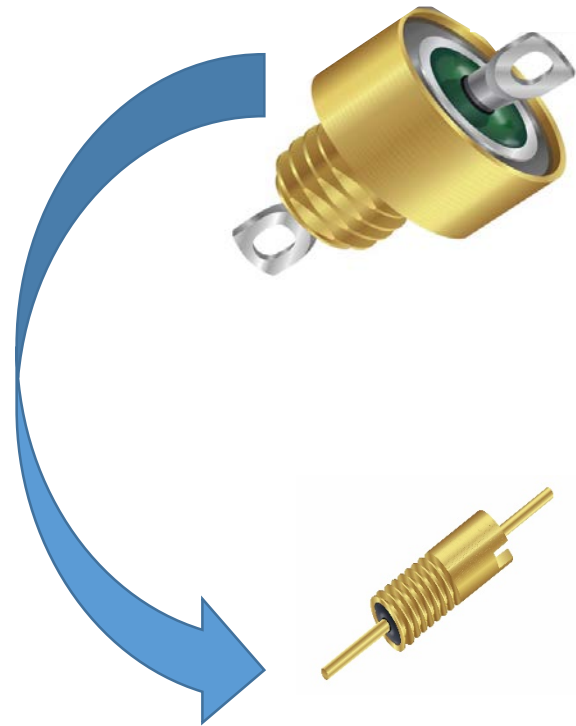
Downsized Filter Performance

- Identical Electrical Responses
- 64% less weight
- 45% less foot print
- 70dB notch still available
- >/ 100v and up to 5amp available

Accelerated progress expected



MLCC advances impact on inserts:



Filter Type	Dia. mm	Max Cap nf	Current	Voltage	Frequency	Weight g	Volume cc	Configuration
Miniature Solder in	3.05	50	5 amp	200 v	10mhz – 10 Ghz	0.0948	0.0204	C, L
Miniature Bolt in	2.67	27	5 amp	200 v	10mhz – 10 Ghz	0.1434	0.0225	C, L, <i>Pi</i>
Sub-miniature Solder in	2.67	27	2.5 amp	200 v	10mhz – 10 Ghz	0.0796	0.0145	C, L
Sub-miniature Bolt in	2.18	5	3 amp	200 v	10mhz – 10 Ghz	0.0902	0.0139	C, L, <i>Pi</i>
Micro-Miniature Solder in	1.90	5	1.5 amp	200 v	10mhz – 10 Ghz	0.0336	0.0056	C, L
Micro-Miniature Bolt in	1.85	5	3 amp	200 v	10mhz – 10 Ghz	0.0591	0.0097	C, L, <i>Pi</i>

Small Filter performance comparison

			Attenuation (dB) @ Mhz					
Filter Type & Size (dia.)		Current (a)	10	30	100	300	1000	10,000
Small standard	4.19 mm	5	15		34		50	60
Miniature	3.05 mm	5	15	22	35	45	55	60
Sub Miniature	2.67 mm	2.5	15	22	35	45	55	60
Micro Miniature	1.9 mm	1.5	15	22	35	45	55	60

Bulk Head Filter Future trends:

Increased CV / Smaller Size

Higher & Lowered Q response efforts

Multiple Response Filter

Pulse capable – slow & fast (ESD) waveform ratings

Novel Configurations – Clamp $>2\text{kA}$ $8 \times 20\mu\text{s}$ $< 5\text{cc}$ volume

Summary

- MLCC progress will continue to drive discoidal capacitors
- Small discoidal capacitors will enable miniature Bulk Head Filters
- Bulk Head filters packaging will broaden – smaller to big
- Filter plate assemblies will become more viable options
- Filter functions expanding – multi response to **clamping**